

AZ nLOF 2020 Photoresist

➤ Negative photoresist without flood exposure

➤ Lithography process

- Spin coating photoresist
- Soft bake at 110°C for 60 – 90s
- Exposure: 365 nm sensitive
- Post Expose Bake: 110°C for 60s
- Developer: AZ 300 MIF and AZ 726 MIF

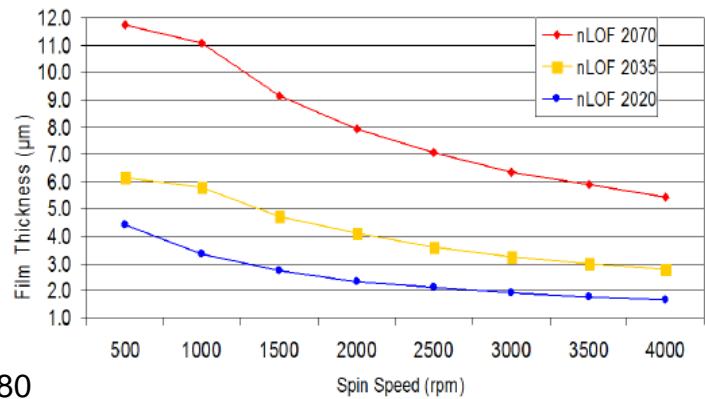
➤ Removers

- AZ 400T, AZ Kwik Strip, or AZ Remover 880

➤ Exposure/PEB profile by the manufacturer

- Prime: HMDS 140°C for 60 s (vapor)
- Soft Bake: 110°C/60s on hotplate
- Exposure i-line (Nikon Stepper)

SPIN CURVES (150MM Silicon)

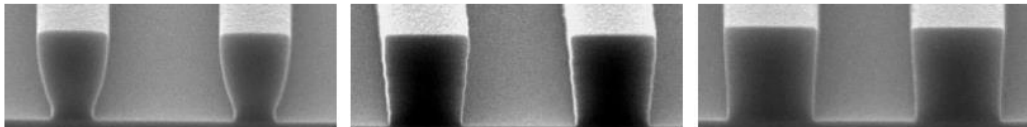


PEB 105C

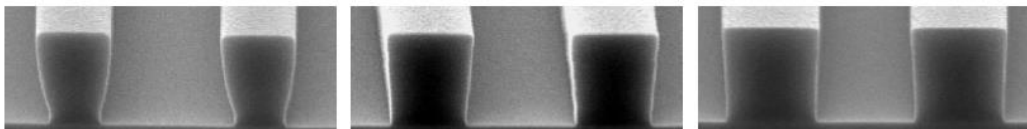
PEB 110C

PEB 115C

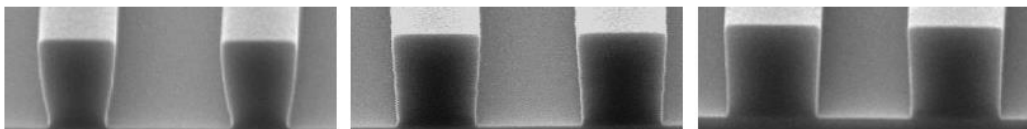
60mJ/cm²



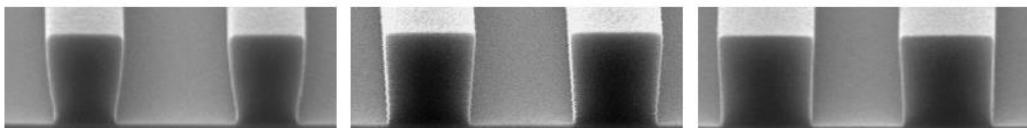
70mJ/cm²



80mJ/cm²



90mJ/cm²



100mJ/cm²

